



Material Content Data Sheet



Halogen-Free

Sales Product Name	ESD108-B1-CSP0201 E6327	Issued	04. May 2021
MA#	MA001126876		
Package	SG-WLL-2-1	Weight*	0.07 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.063	92.48	92.48	924808	924808
pad	inorganic material	silicon	7440-21-3	0.000			15	
	non noble metal	copper	7440-50-8	0.000			29	
	inorganic material	phosphorus	7723-14-0	0.000	0.08		838	
	non noble metal	aluminium	7429-90-5	0.000	0.34		3366	
	noble metal	palladium	7440-05-3	0.001	1.10		10996	
	noble metal	gold	7440-57-5	0.001	1.77		17699	
	non noble metal	nickel	7440-02-0	0.003	4.04	7.33	40368	73311
passivation	inorganic material	silicon dioxide	60676-86-0	0.000	0.07		676	
	inorganic material	silicon nitride	12033-89-5	0.000	0.12	0.19	1205	1881
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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